

In the Claims:

Please cancel claims 1-10, without prejudice.

1-10. (Cancelled)

11. (Original) A testing method for a head IC comprising:

a step of installing a head IC for processing an electric signal from a head for at least reading a disk medium, on a head suspension that supports said head; and

a step of placing a probe on a terminal of said head suspension to check electric characteristics of said head IC.

12. (Original) The testing method of claim 11 wherein said head suspension comprises:

a first connection terminal for electrically connecting to said head;

a second connection terminal for connecting to external circuits;

third and fourth connection terminals for electrically connecting to said head IC;

a first conductive path that connects said first and third connection terminals;

and

a second conductive path that connects said second and fourth connection terminals; and

a measurement terminal that is located between said second connection terminal and said fourth connection terminal of said second conductive path, and which is placed said probe.

13. (Original) The testing method of claim 11 wherein;
said measurement terminal and said first connection terminal are located such that they are on the same plane of said suspension.

14. (Original) The testing method of claim 11 wherein;
said first, second, third and fourth connection terminals, said first and second conductive paths, and said measurement terminal are formed using a thin-film pattern on the base of said suspension.

15. (Original) The testing method of claim 11 further comprising:
a base for said head suspension; and
a flexible cable on which said first, second, third and fourth connection terminal, said first and second conductive paths and said measurement terminal are formed.

16. (Original) The testing method of claim 11 wherein said head comprises a magnetic head.

17. (Original) A manufacturing method for HGA comprising:

- a step of installing a head IC for processing an electric signal from a head for at least reading a disk medium, on a head suspension that supports said head;
- a step of placing a probe on a terminal of said head suspension to check electric characteristics of said head IC; and
- a step of installing a head on said head suspension with said head IC.